

Welcome to **E-XFL.COM**

Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	4 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	24
Number of Macrocells	96
Number of Gates	4000
Number of I/O	96
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	128-LQFP
Supplier Device Package	128-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/isplsi-2096ve-250lt128

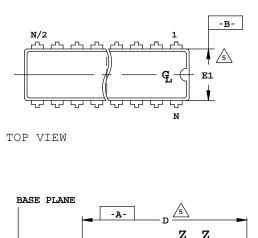
Email: info@E-XFL.COM

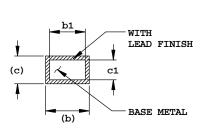
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



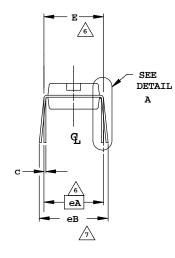
20-Pin Plastic DIP Package

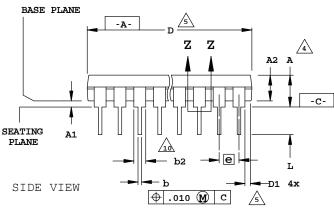
Dimensions in Inches

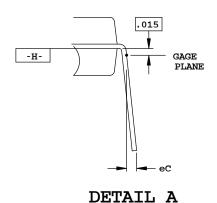




SECTION Z-Z







NOTES:

- 1. CONTROLLING DIMENSION: INCH.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
- 3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR
- PROTRUSIONS TO BE .005 MINIMUM. DIMENSIONS A, A1 & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING
- PLANE GAUGE GS-3.
- PLANE GAGE GS-3.

 DIMENSIONS D, D1 AND E1
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010

 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED

 TO BE PERPENDICULAR TO DATUM C-
- 70 BE PERPENDICULAR TO DATOM.

 eB AND eC ARE MEASURED AT THE LEAD TIPS

 with the Leads unconstrained.
- 8. N IS THE MAXIMUM NUMBER OF LEAD
- POSITIONS.

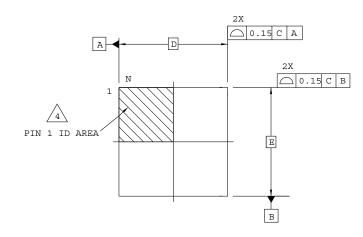
 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
- 10 b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
- 11 DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

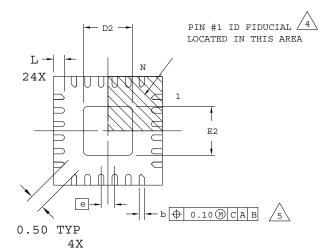
]			
s Y M B	I	INCHES		
o L	MIN.	NOM.	MAX.	N O T
Α	-	-	.210	4
A 1	.015	-	-	4
A 2	.115	.130	.195	
b	.014	.018	.022	
b1	.014	.018	.020	
b2	.045	.060	.070	10
C	.008	.010	.014	
C1	.008	.010	.011	
D	.980	1.030	1.060	5
D1	.005	1	-	5
Е	.300	.310	. 325	6
E1	.240	.250	.280	5
е	.100 BSC			
eА	.300 BSC			6
еВ	-		.430	7
eС	.000	-	.060	7
ь	.115	.130	.150	4
ய	.115	.130	.130	-



24-Pin QFNS Package

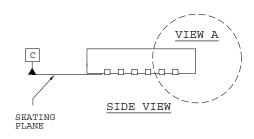
Dimensions in Millimeters

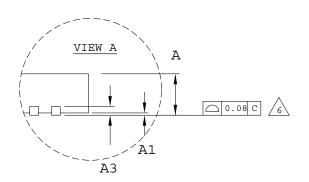




TOP VIEW

BOTTOM VIEW





NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- 3. DRAWING CONFORMS TO JEDEC MO-220, VARIATION VGGD-9.

 $\sqrt{4}$

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

5

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

6

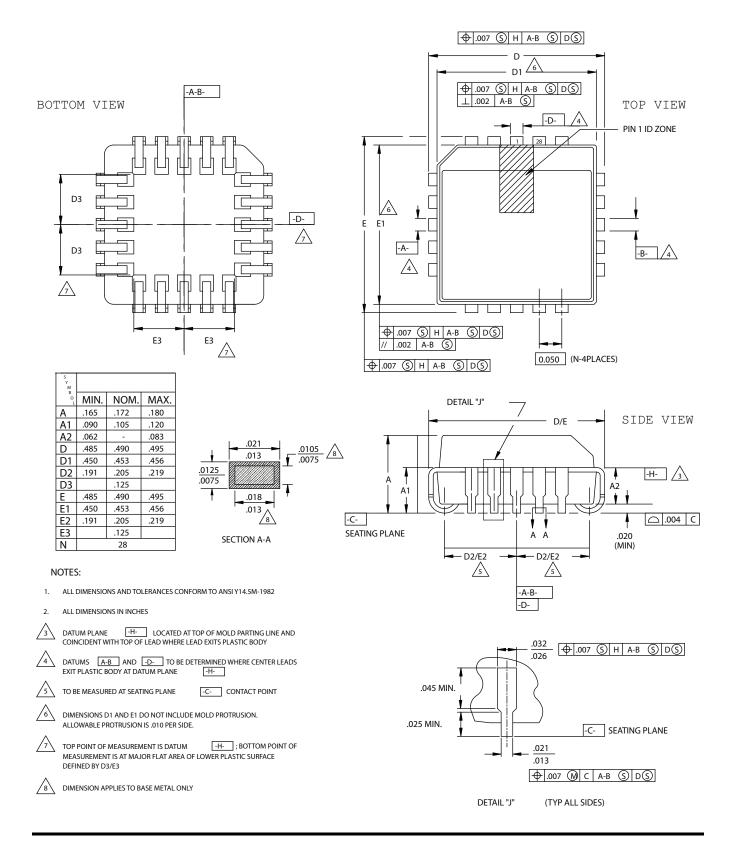
APPLIES TO EXPOSED PORTION OF TERMINALS.

SYMBOL	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	4.0 BSC		
D2	1.05	-	2.45
E	4.0 BSC		
E2	1.05	-	2.45
b	0.18	0.25	0.30
е	0.50 BSC		
L	0.45	0.50	0.55



28-Pin PLCC Package

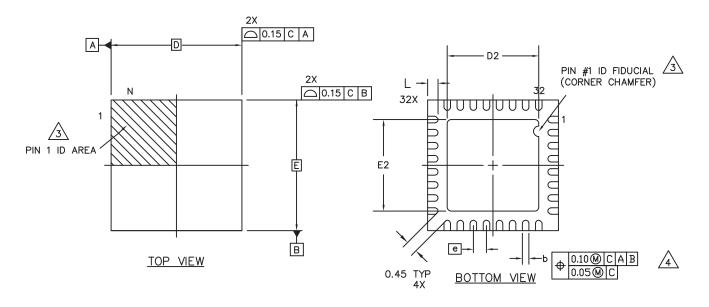
Dimensions in Inches

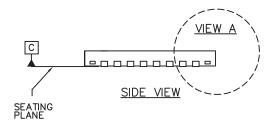


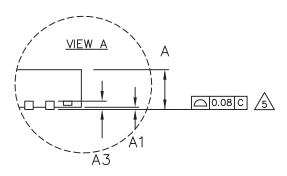


32-Pin QFN Package Option 3: MachXO2 SG32C

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

 $\stackrel{\textstyle \frown}{}$ Applies to exposed portion of terminals.

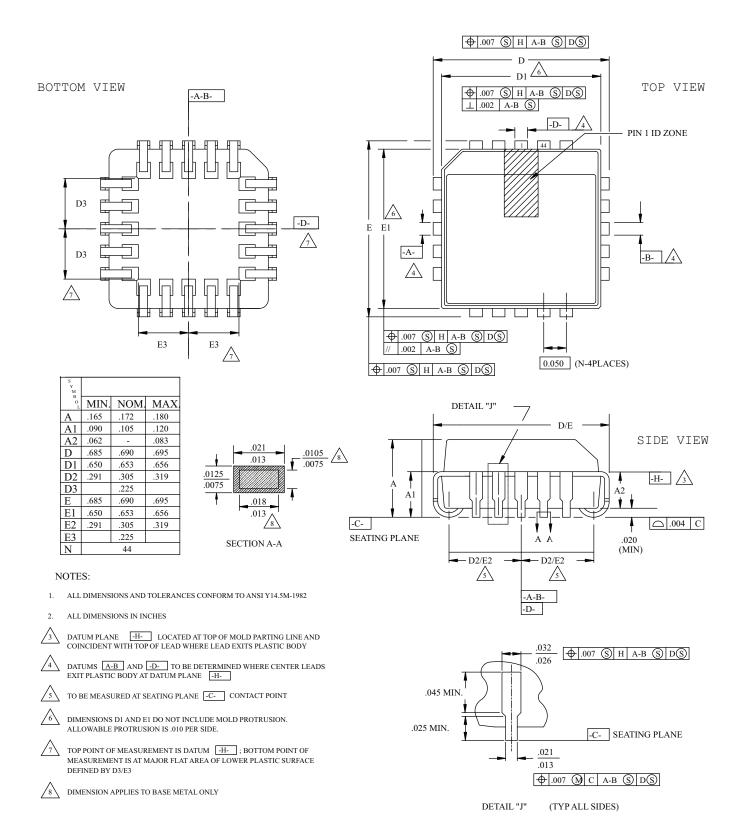
6. JEDEC REFERENCE MO-248 AND DR-4.2

SYMBOL	MIN.	NOM.	MAX.
А	0.50	0.55	0.65
A1	0.00	0.02	0.05
A3	0.2 REF		
D	5.0 BSC		
D2	3.40	3.50	3.60
E	5.0 BSC		
E2	3.40	3.50	3.60
b	0.18	0.25	0.30
е	0.50 BSC		
L	0.35	0.40	0.45



44-Pin PLCC Package

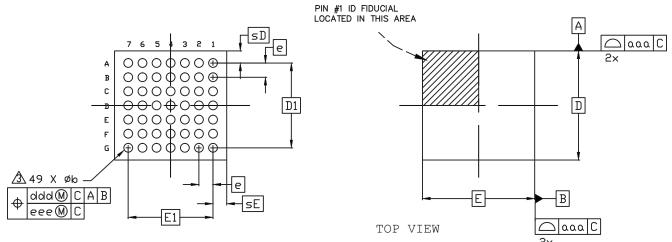
Dimensions in Inches



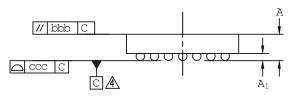


49-Ball WLCS Package

Dimensions in Millimeters



BOTTOM VIEW



SIDE VIEW

Notes:

- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- A PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.

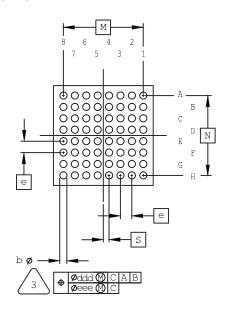
REF.	Min.	Nom.	Max.
A	_		0.600
A1	0.167	0.199	0.232
b	0.239	0.266	0.319
D	3.055	3.106	3.155
E	3.125	3.185	3.225
D1	2.40 BSC		
E1	2.40 BSC		
е	0	.40 BSC	
sD	0.353	_	0.383
sE	0.388	-	0.418
aaa	(0.030	
bbb	(0.060	
ccc	0.050		
ddd	0.015		
eee	(0.050	
	•		

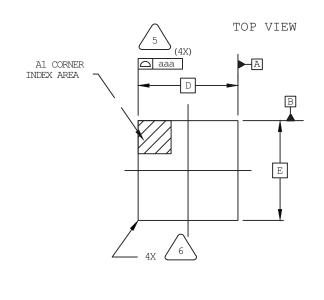


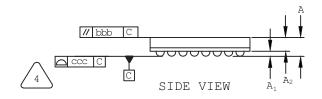
64-Ball ucfBGA Package

Dimensions in Millimeters

BOTTOM VIEW







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

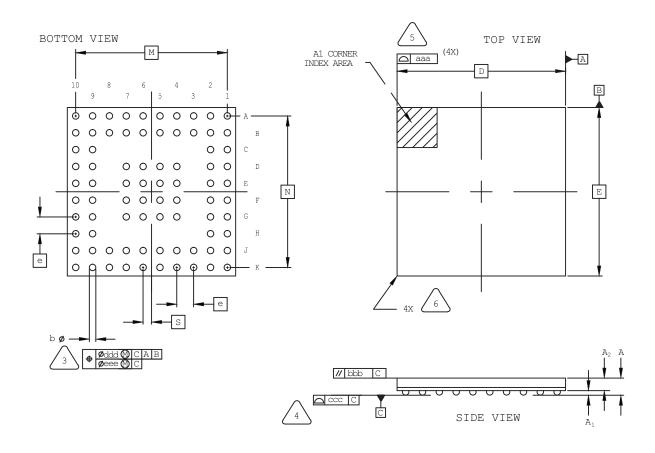


SYMBOL MIN. NOM. MAX. A - - 1.00 A1 0.11 - - A2 0.62 - -			
A1 0.11			
A2 0.62			
D/E 3.50 BSC			
M/N 2.80 BSC			
S 0.20 BSC			
b 0.20 0.25 0.30			
e 0.40 BSC	0.40 BSC		
aaa 0.10	0.10		
bbb 0.10	0.10		
ccc 0.08	0.08		
ddd 0.15	0.15		
eee 0.08	0.08		



80-Ball ctfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\boxed{\mathbb{C}}$.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

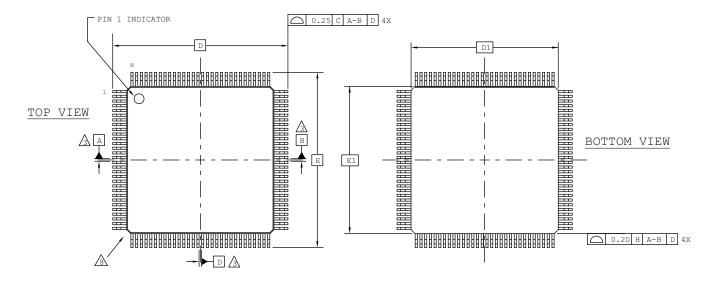


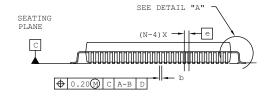
SYMBOL	MIN.	NOM.	MAX.
А	1	-	1.00
A1	0.11	-	ı
A2	0.61	-	-
D/E		6.50 BSC	
M/N		5.85 BSC	
S	0.325 BSC		
b	0.20 0.25 0.30		
е	0.65 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee		0.05	

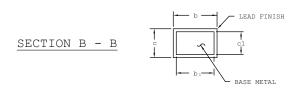


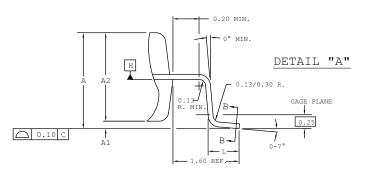
120-Pin PQFP Package

Dimensions in Millimeters









NOTES:

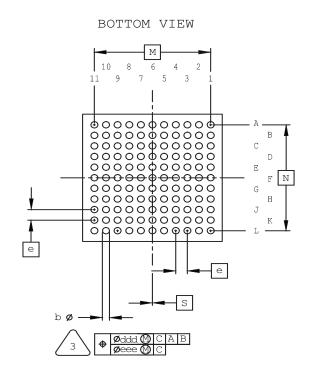
- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- A DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 4.0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- $\stackrel{\textstyle \wedge}{\underline{\mathop{\otimes}}}$ exact shape of each corner is optional.
- SEXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

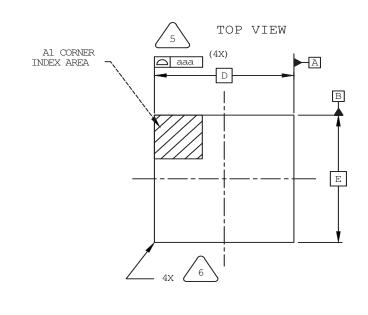
SYMBOL	MIN.	NOM.	MAX.
A	-	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D		31.20 BSC	
D1		28.00 BSC	!
E	31.20 BSC		
E1	28.00 BSC		
L	0.73	0.88	1.03
N	120		
е	0.80 BSC		
b	0.29	-	0.45
b1	0.29	0.35	0.41
С	0.11	-	0.23
c1	0.11	0.15	0.19

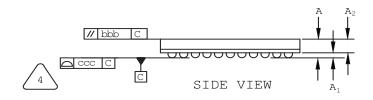


121-Ball csfBGA Package

Dimensions in Millimeters







NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



PRIMARY DATUM $\overline{\mathbb{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

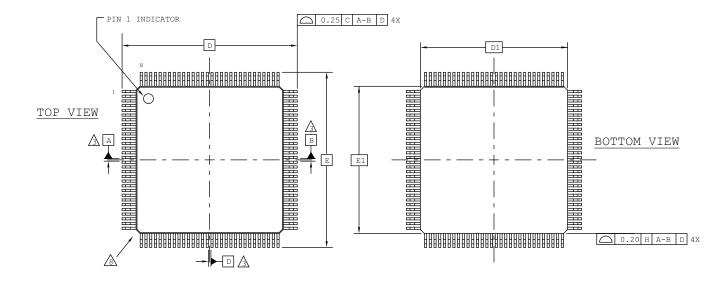


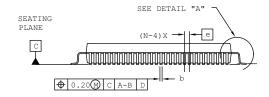
SYMBOL	MIN.	NOM.	MAX.
А	_	_	1.00
A1	0.15	0.24	_
A2	_	0.66	-
D/E		6.00 BSC	
M/N		5.00 BSC	
S	0.00 BSC		
b	0.25 0.30 0.35		
е	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee		0.05	

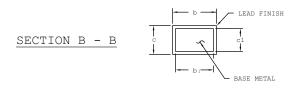


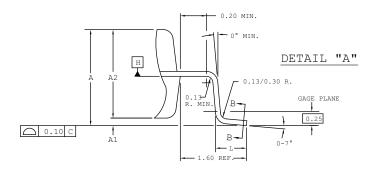
128-Pin PQFP Package

Dimensions in Millimeters









NOTES:

- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- A DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 4.0 DIMENSIONS D1 AND E1 D0 NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6.0 SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



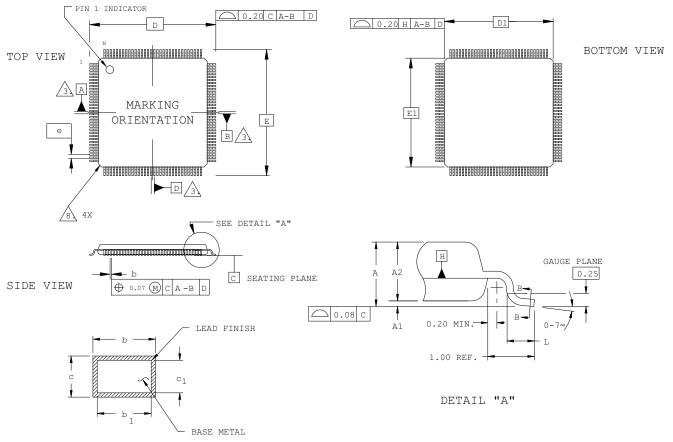
♠ EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D		31.20 BSC	!
D1		28.00 BSC	
E	31.20 BSC		
E1	28.00 BSC		
L	0.73	0.88	1.03
N	128		
е	0.80 BSC		
b	0.29	-	0.45
b1	0.29	0.35	0.41
С	0.11	-	0.23
с1	0.11	0.15	0.19



128-Pin TQFP Package

Dimensions in Millimeters



SECTION B - B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

A DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
 ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

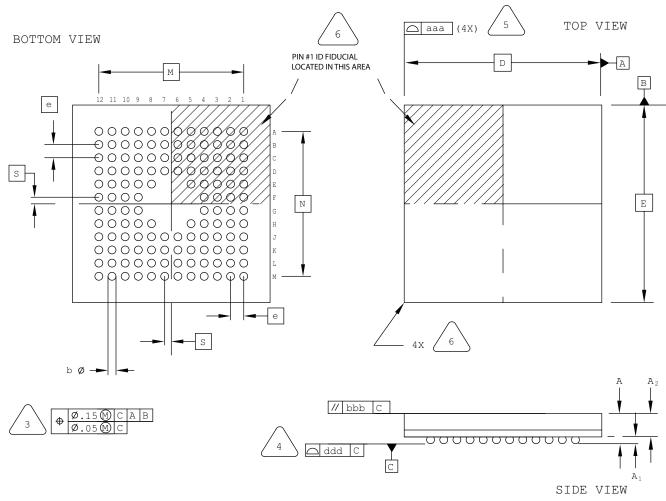
SIDE VIEW

SYMBOL	MIN.	NOM.	MAX.
A	=	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	16.00 BSC		
D1	14.00 BSC		
E	16.00 BSC		
E1	14.00 BSC		
L	0.45	0.60	0.75
N	128		
е		0.40 BSC	
b	0.13	0.18	0.23
b1	0.13	0.16	0.19
С	0.09	0.15	0.20
c1	0.09	0.13	0.16



132-Ball ucBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

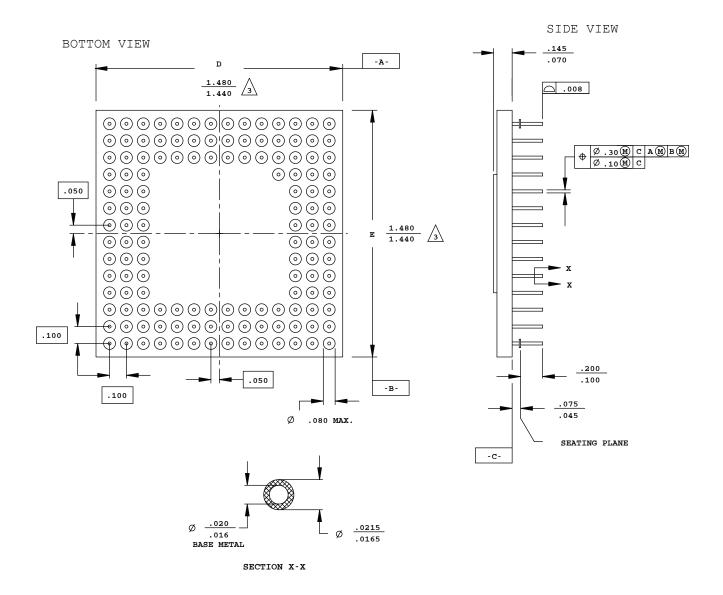


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	6.00 BSC		
M/N	4.40 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
е	0.40 BSC		
aaa	-	-	0.10
bbb	_	_	0.10
ddd	_	_	0.08



133-Pin CPGA Package

Dimensions in Inches



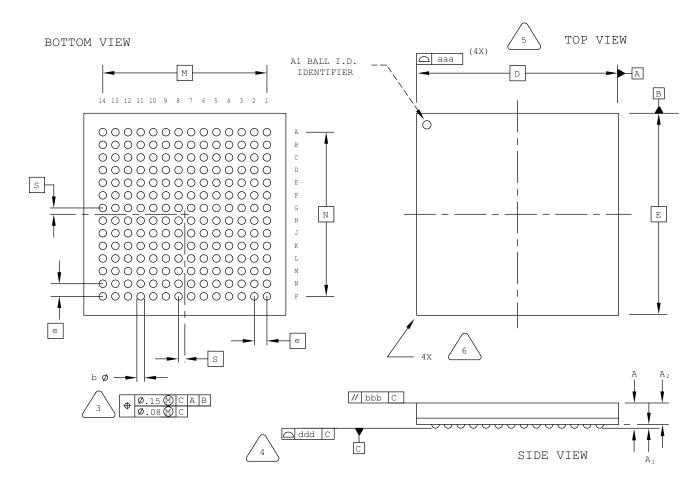
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- DIMENSIONS D AND E MAY HAVE MATERIAL PROTRUSION OF
 .006 INCHES MAXIMUM ABOVE THE DIMENSION SHOWN
 NOT TO EXCEED .003 INCHES MAXIMUM PER SIDE.



196-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

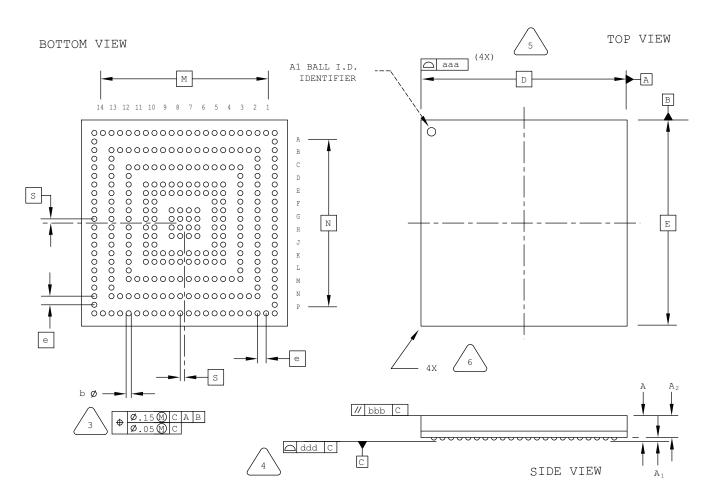


SYMBOL	MIN.	NOM.	MAX.
А	ı	-	1.00
A1	0.15	_	_
A2	-	_	0.85
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
е	0.50 BSC		
aaa	-	_	0.10
bbb	-	_	0.10
ddd	_	_	0.08



284-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

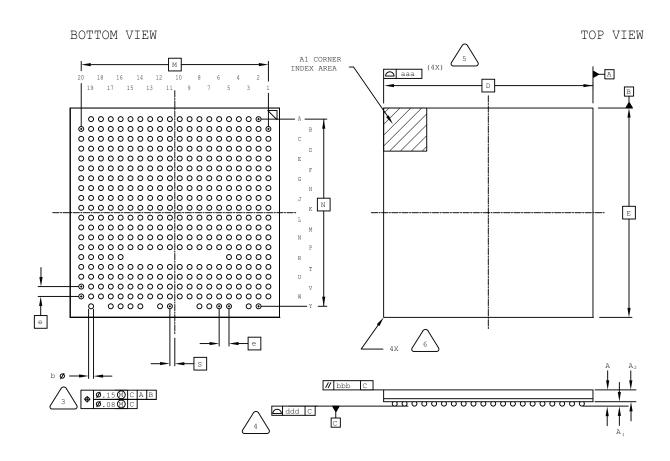


SYMBOL	MIN.	NOM.	MAX.
А	ı	-	1.00
A1	0.15	-	ı
A2	_	-	0.85
D/E	12.00 BSC		
M/N	10.50 BSC		
S	0.25 BSC		
b	0.25	0.31	0.37
е	0.50 BSC		
aaa	-	_	0.10
bbb	_	_	0.10
ddd	_	_	0.08



381-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

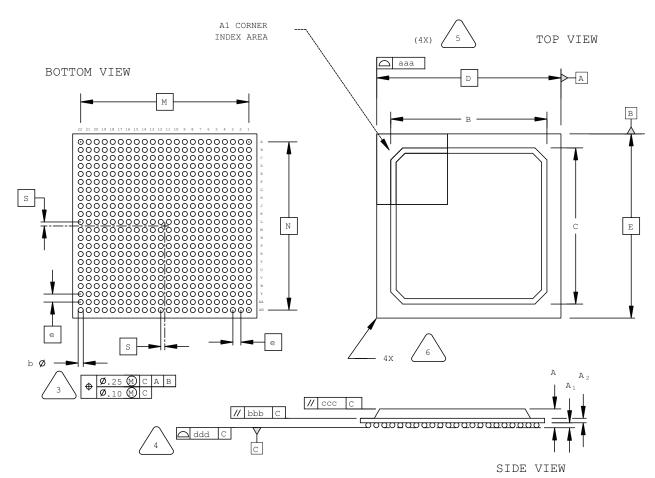


SYMBOL	MIN.	NOM.	MAX.
А	ı	ı	1.76
A1	0.25	0.30	0.35
A2	0.80	ı	ı
D/E	17.00 BSC		
M/N	15.20 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
е	0.80 BSC		
aaa	_	-	0.15
bbb	-	-	0.20
ddd	_	_	0.12



484-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\fbox{\colored{C}}$



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

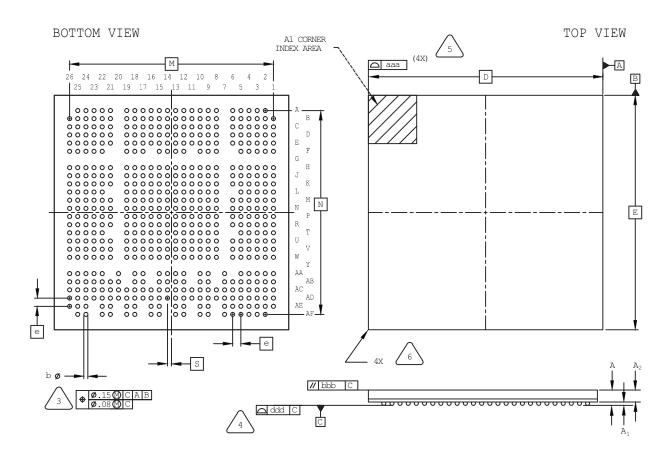


SYMBOL	MIN.	NOM.	MAX.
А	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	19.30	19.80	20.30
D/E	23.00 BSC		
M/N	21.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	_	0.20
bbb	-	_	0.25
ccc	-	-	0.35
ddd	-	-	0.20



554-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{3}$

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

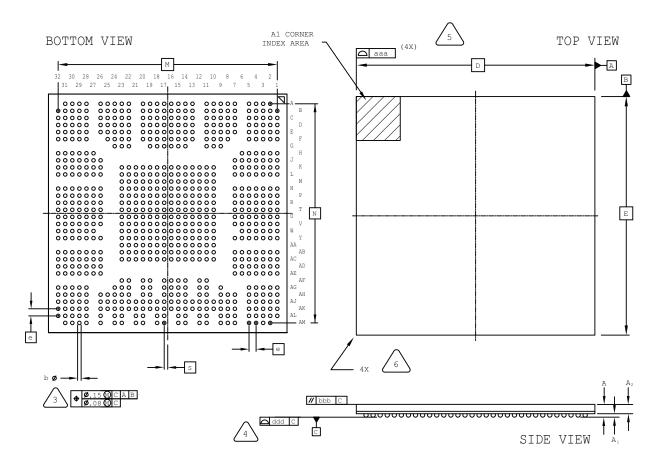


SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	ı	ı
D/E	23.0 BSC		
M/N	20.0 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
е	0.80 BSC		
aaa	_	-	0.15
bbb	_	. 1	0.20
ddd	_		0.12



756-Ball caBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	-
D/E	27.00 BSC		
M/N	24.80 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
е	0.80 BSC		
aaa	_	_	0.15
bbb	_	-	0.20
ddd	_	-	0.12